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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10053278	01/16/2002	228	180.22	1725	Stoner

**APPLICANTS: Byun Hyung-Jik; Lee Kyu-Jin;

**CONTINUING DATA VERIFIED: none KS

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** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 2001-5383 02/05/2001 OK KS

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		9903-40	
Verified and Acknowledged Examiners's initials <i>[Signature]</i>			
TITLE : Semiconductor chip package comprising enhanced pads			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
Primary Examiner		Application Examiner	
PREPARED FOR ISSUE			
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